

ABSTRACT OF THE DISCLOSURE

Optoelectronic packaging assemblies for optically and electrically interfacing an electro-optical device to an optical fiber and to external circuitry. An optoelectronic packaging assembly includes a submount for holding an optical bench with an electro-optical device. Electrically conductive pins provide electrical contact to the electro-optical device.

The optoelectronic packaging assembly includes an optical input receptacle for receiving an optical ferrule and an optical fiber. The optical input receptacle assists optical coupling of the electro-optical device to the optical fiber. The optoelectronic packaging assembly provides for cooling using a heat-sink or a thermal-electric-cooler. Beneficially, the optoelectronic packaging assembly is sealed using a cover.